

electrodes; and

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Coul
at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the metal posts, wherein the mark member is made of the same material as the metal posts; and wherein the first shape and the first size are correspondingly different from the second shape and the second size.

4. (Amended) A semiconductor device comprising:

D2
a semiconductor element having a plurality of electrodes;

a redistribution layer which connects the electrodes of the semiconductor device to a plurality of electrode pads each with a first shape and a first size located in predetermined positions of the redistribution layer; and

Ref
F1
at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the electrode pads; wherein the mark member is made of the same material with the electrode pads; and wherein the first shape and the first size are correspondingly different from the second shape and the second size.

13. (Three-times Amended) An apparatus for fixing a semiconductor wafer by suction, comprising:

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Sub
F1

a vacuum chuck table having a porous plate overlaying a plurality of concentric suction grooves;

a plurality of suction passages each being connected to the plurality of concentric suction grooves each barometrically independent from another; and

suctioning device for sequentially introducing a suctioning force into the suction passages at different timing.

14. (Amended) A semiconductor device comprising:

a semiconductor element having a plurality of electrodes;

a redistribution layer having a plurality of electrode pads and conductive patterns connecting the electrodes of the semiconductor element to the respective electrode pads;

a plurality of metal posts with a first shape and a first size formed on the electrode pads of the redistribution layer, the metal posts being configured to be provided with external connection electrodes; and

at least one mark member with a second shape and a second size which serves as an alignment mark located in a predetermined positional relationship with the metal posts;

wherein the first shape and the first size are correspondingly different from the second shape and the second size.

D3
Final

Please add new claim 15 as follows:

15. (New) A semiconductor device comprising:

a semiconductor element having a plurality of electrodes;

a redistribution layer having a plurality of electrode pads and conductive patterns connecting

the electrodes of the semiconductor element to the respective electrode pads;

a plurality of metal posts formed on the electrode pads of the redistribution layer;

at least one electrode part comprising one of the metal posts and a protruding electrode attached to a top of the one of the metal posts; and

at least one mark member which serves as an alignment mark located in a predetermined positional relationship with the electrode part, the mark member comprising one of the metal posts but lacking the protruding electrode.